Panasonic

Zener Diode

DZ2J200×0L Silicon epitaxial planar type

For constant voltage / For surge absorption circuit

Features

- · Excellent rising characteristics of zener current Iz
- Low zener operating resistance Rz
- Halogen-free / RoHS compliant (EU RoHS / UL-94 V-0 / MSL:Level 1 compliant)
- Marking Symbol: ZJ or ZU

Packaging

Embossed type (Thermo-compression sealing): 3 000 pcs / reel (standard)

Absolute Maximum Ratings	Ta = 25 °	°C	
Parameter		Symbol	

Repetitive peak forward current	IFRM	200	mA
Total power dissipation ^{*1}	PT	200	mW
Electrostatic discharge *2	ESD	±8	kV
Junction temperature	Tj	150	С°
Operating ambient temperature	Topr	-40 to +85	С°
Storage temperature	Teta	-55 to +150	°C

 Storage temperature
 I stg
 -55 to
 +150
 °C

 Note)
 *1
 Mounted on glass epoxy print board (45 mm × 45 mm × 1 mm) Solder in (Recommended land pattern)

*2 Test method : IEC61000_4_2

(C = 150 pF, R = 330 Ω , Contact discharge : 10 times)

■ Electrical Characteristics Ta = 25 °C ± 3 °C

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Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Forward voltage	VF	IF = 10 mA			1.0	V
Zener voltage ^{*1, *2}	VZ	IZ = 5 mA	19.00		21.00	V
Zener operating resistance	RZ	IZ = 5 mA			80	Ω
Zener rise operating resistance	RZK	IZ = 0.5 mA			100	Ω
Reverse current	IR	VR = 15 V			0.05	μA
Temperature coefficient of zener voltage *3	SZ	IZ = 5 mA		18.4		mV/°C

Rating

Unit

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 Measuring methods for Diodes.

2. Absolute frequency of input and output is 5 MHz.

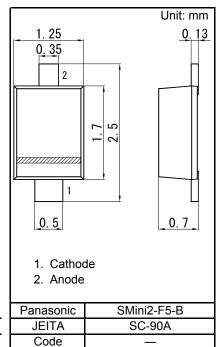
3. *1 The temperature must be controlled 25 °C for VZ mesurement.

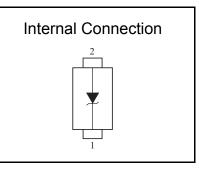
VZ value measured at other temperature must be adjusted to VZ (25 °C).

*2 VZ guaranted 20 ms after current flow Rank classification

*3	Tj = 25 °C to 150 °C	



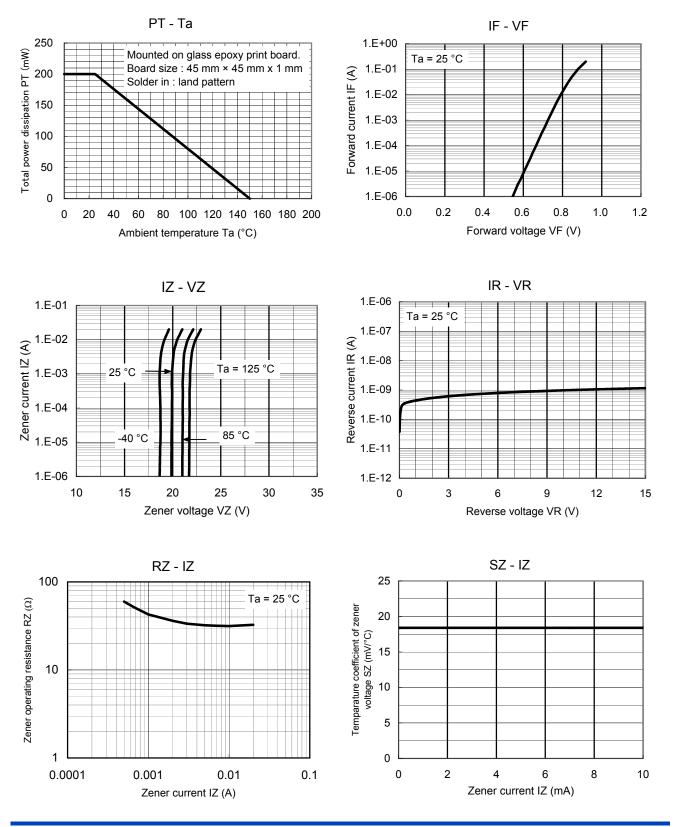






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Technical Data (reference)

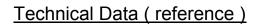


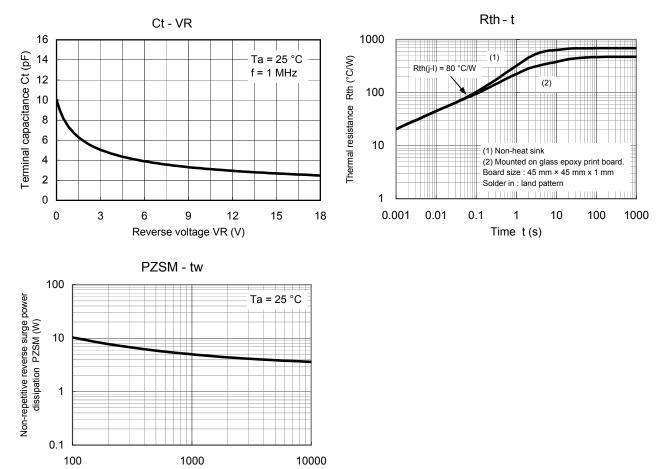
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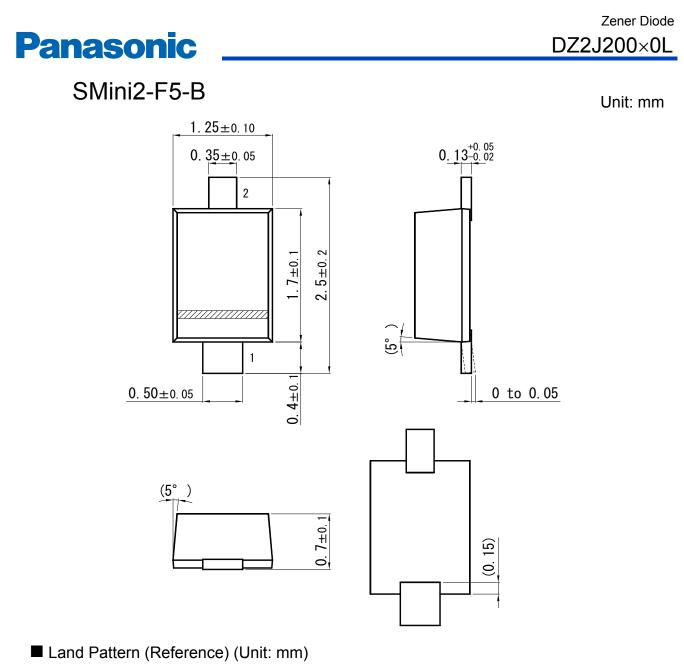
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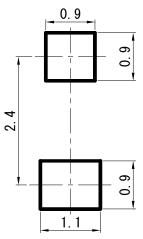






Pulse width tw (µs)





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